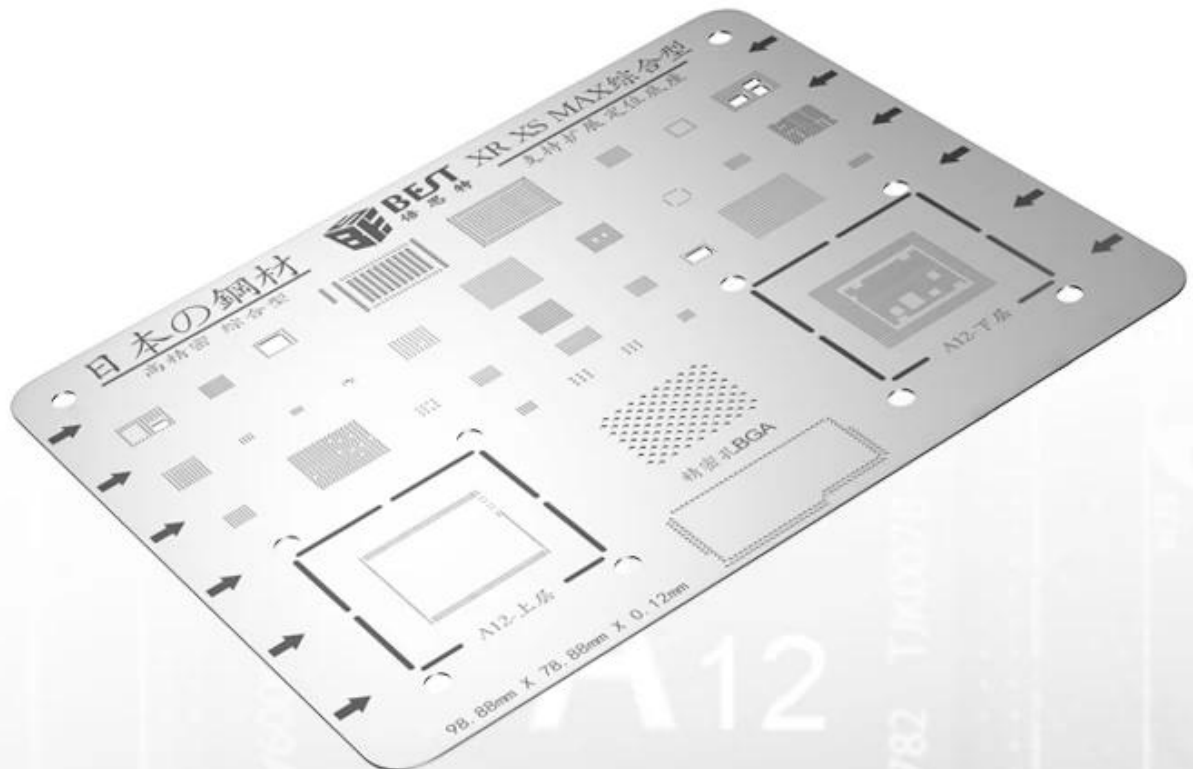


REBALLING STENCIL

— iPhone CPU series —



SEMI-ETCHING PROCESS



COOLING HOLE DESIGN



PRECISE ALIGNMENT



SQUARE HOLE

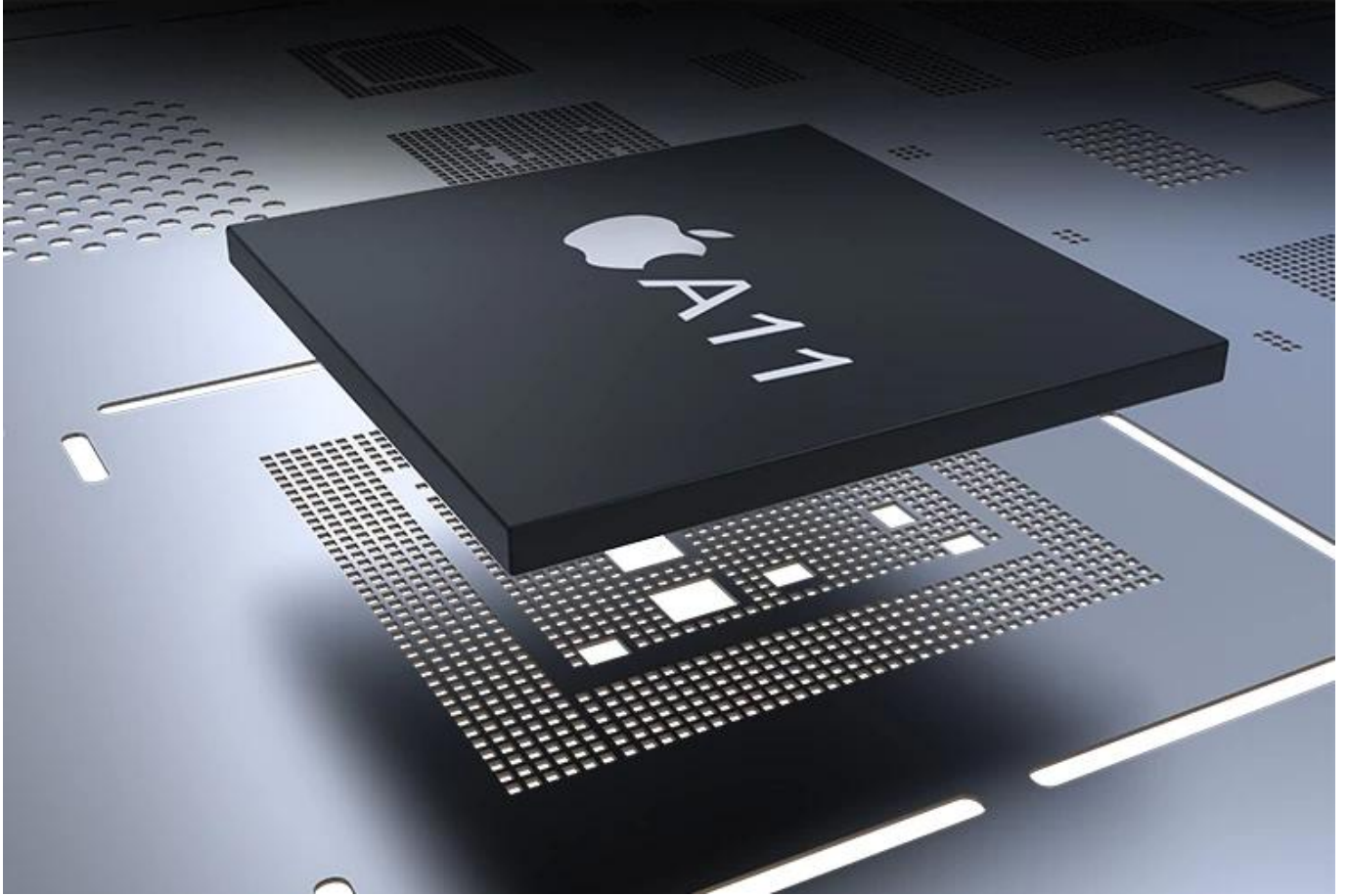


IMPORTED STEEL

HIGH TOUGHNESS

GOOD PRODUCTS ARE NOT ONLY
EXCELLENT FORGING PROCESSES,
BUT THE REAL CORE LIES IN THE
SELECTION OF DELICATE MATERIALS.

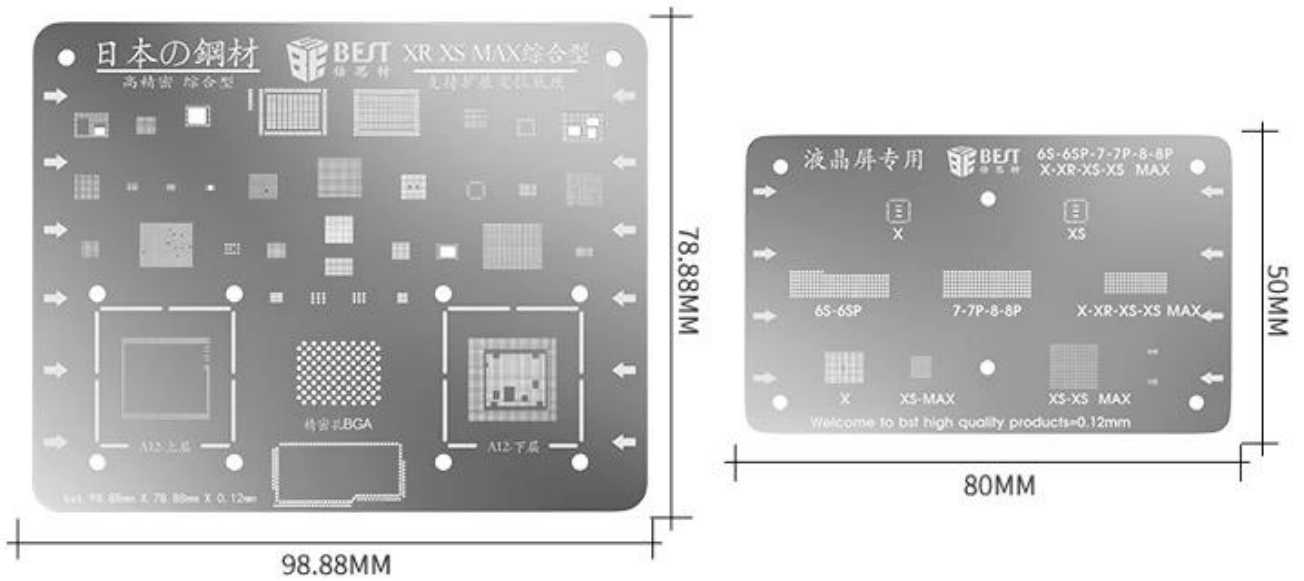
Easily mounted on the steel mesh to make the chip fit more closely with the mesh
Therefore, the chip after tinning is "more precise"



Imported steel
Hard and wear resistant
Accurate to the hole



PRODUCT SIZE



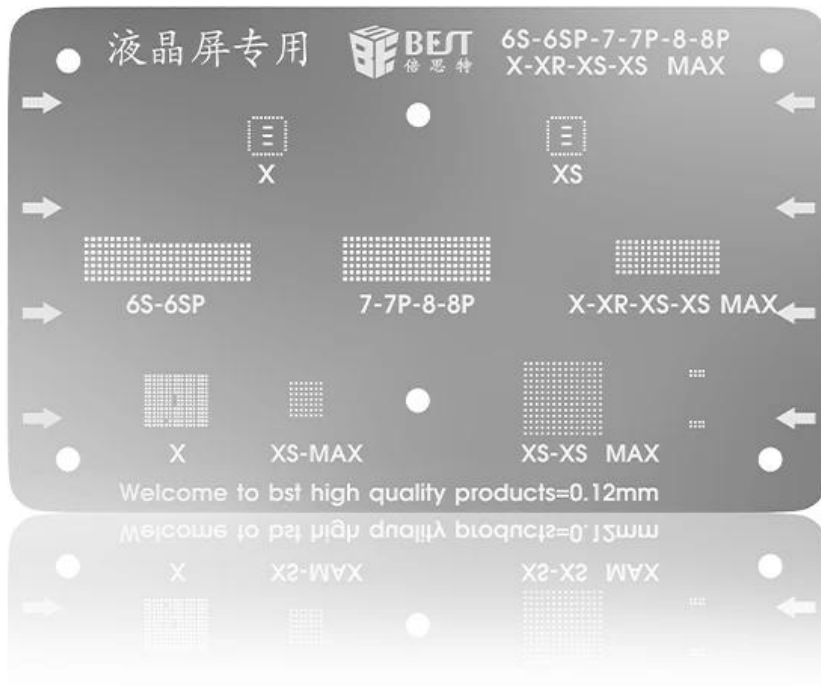
Thin to 0.12mm

Precise die-casting **form heating**

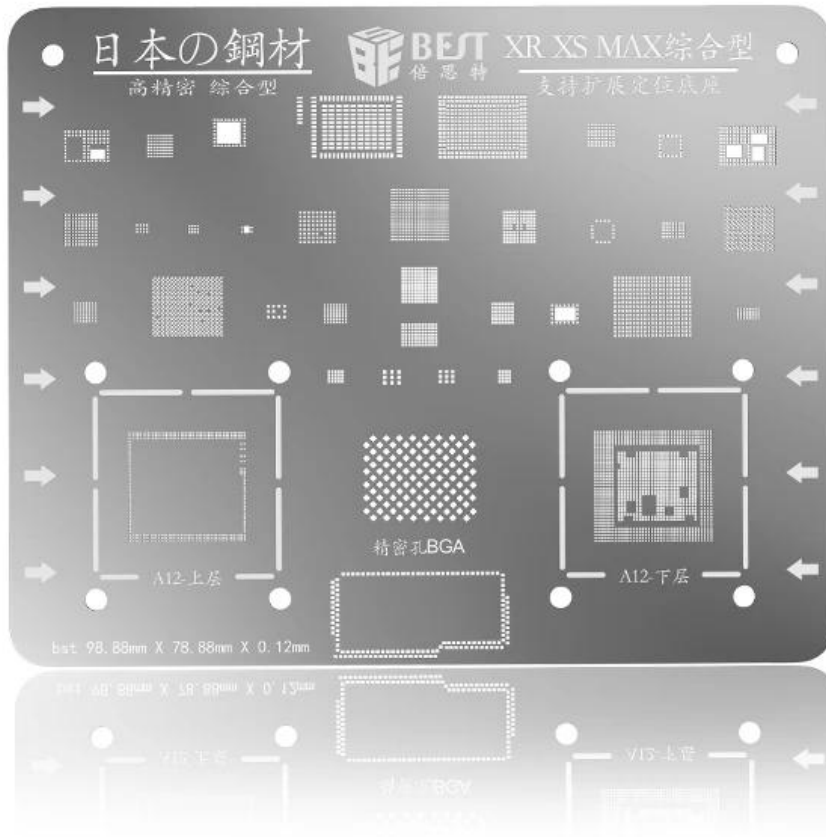


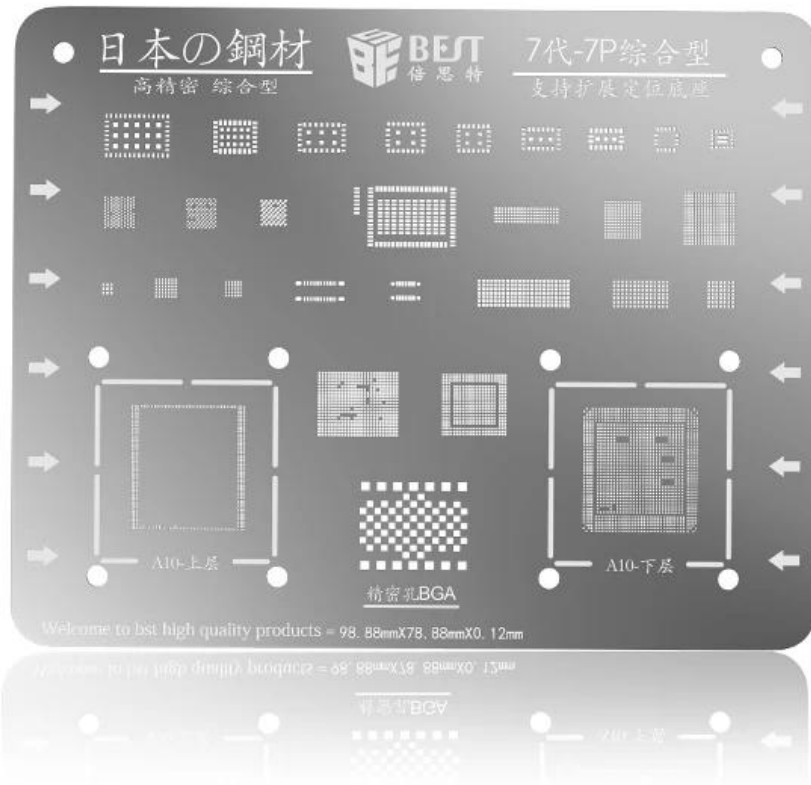
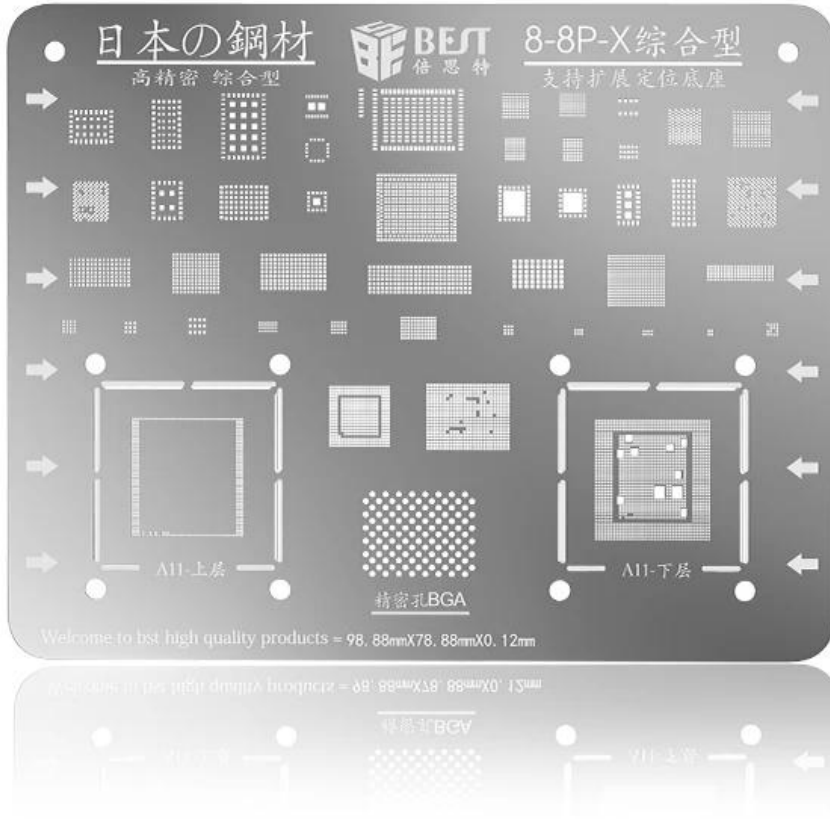


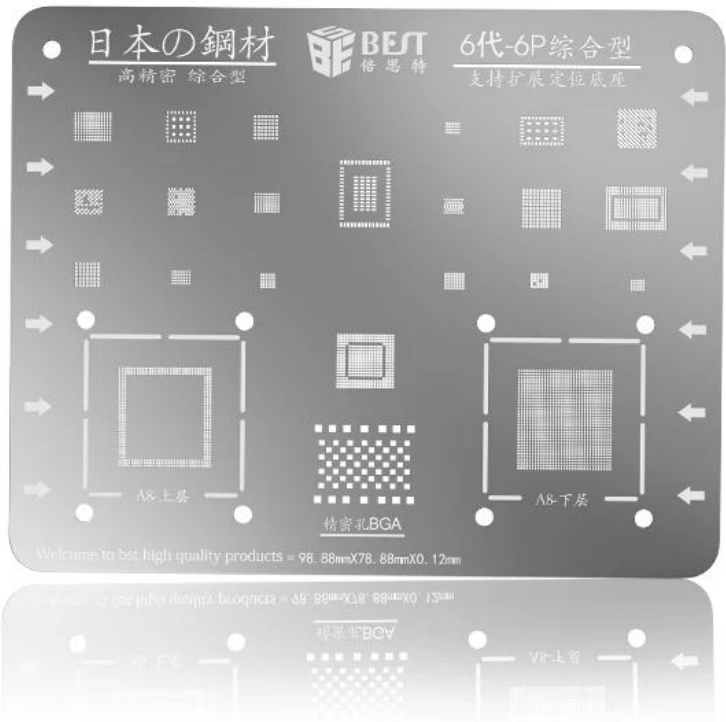
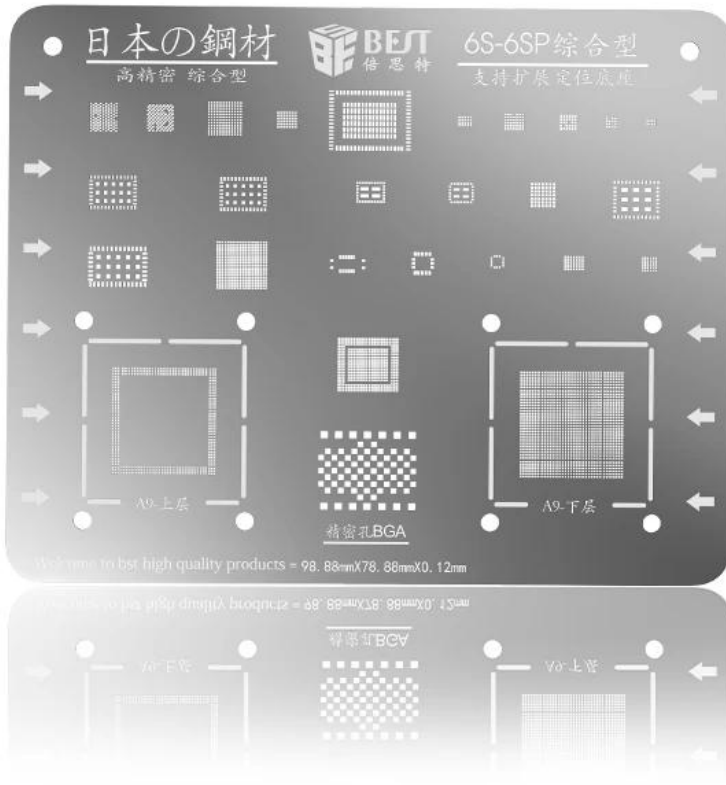
6S-6SP-7-7P-8-8P-X-XR-XS-XS MAX



XR-XS-XS MAX COMPREHENSIVE







● **日本の鋼材** **BEST** **5代-5C/5S综合型** ●
高精密 综合型 倍思特 支持扩展定位底座

A7-上层 精密孔BGA A7-下层

Welcome to bst high quality products - 98. 88mmX78. 88mmX0. 12mm

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